



Product Change Notification

Change Notification #: 117116 - 00
Change Title: Intel® Server System R2312WF0NPR,
Update BIOS/BMC/ME/FRUSDR,
PCN 117116-00, Product Design, Label,
System outer box J33994-001 stacking logo
update, 3.5" Tool-Less Carrier Design
Improvement for 2.5" Drive Support
Date of Publication: August 13, 2019

Key Characteristics of the Change:

Product Design, Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material *:	August 28, 2019
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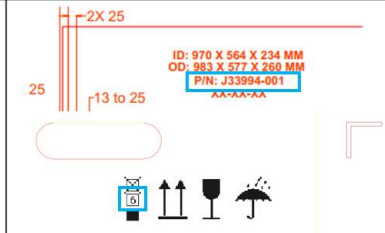

* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following three changes on the Intel® Server System R2312WF0NPR:

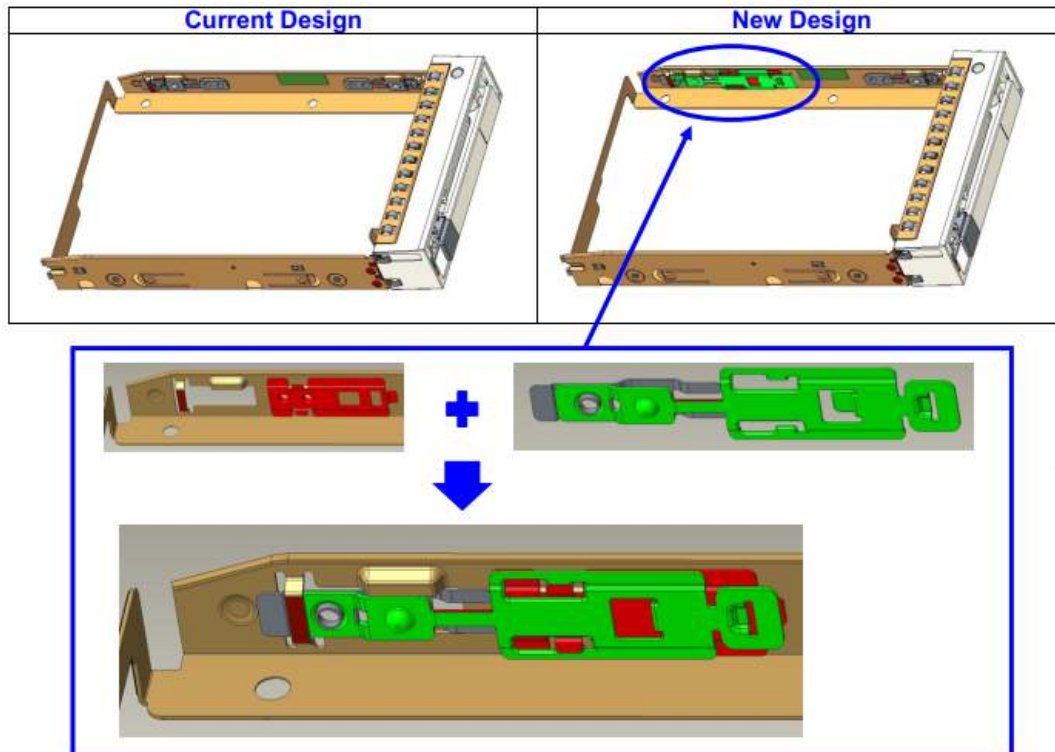
- Update to the system firmware
 - a. Update BIOS revision to R02.01.0008
 - b. Update the Manageability Engine (ME) firmware revision to 04.01.04.251
 - c. Update the Baseboard Management Controller (BMC) firmware revision to 1.93.870cf4f0
 - d. Update the FRUSDR revision to 1.93

- Update to the system outer box stacking logo, original logo mean MAX 7-layers in total, however, only 6-layers as MAX can be supported by logistics racking limitation.

	Original outer box	New outer box
IPN	J33994-001	J33994-002
Description	System outer box with J33994-001 IPN and 6 layers stacking logo printing	Updated system outer box with J33994-002 IPN and 5 layers stacking logo printing
Photos		

- Improvement for the 3.5" tool-less drive carrier when used for 2.5" drive support, from a non-removable to a new removable rear spring (see image in green) and new spring holder (see image in red) attached to the tool-less drive carrier.

Removing the new rear spring of 3.5" tool-less carrier when installing 2.5" SSD drive, installing the rear spring to support 3.5" HDD.



Customer Impact of Change and Recommended Action:

Intel does not expect any other impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA#	Pre Change PBA#	Post Change TA#	Post Change PBA#
R2312WF0NPR	986054	K40016-001	H87179-871 H87179-881	K40016-002	H87179-872 H87179-882

PCN Revision History:

Date of Revision:

August 13, 2019

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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